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- Controlled Baseline

 One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Supports Unregulated Battery Operation Down to 2.7 V
- I_{off} and Power-Up 3-State Support Hot Insertion

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

description/ordering information

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22

 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

PW PACKAGE (TOP VIEW)								
OE [1Q [1D [2D [3Q [3D [4D [4Q [1 2 3 4 5 6 7 8 9 10	σ	20 19 18 17 16 15 14 13 12	V _{CC} 8Q 8D 7D 7Q 6Q 5D 5Q				
GND [10			LE				

This octal latch is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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ORDERING INFORMATION

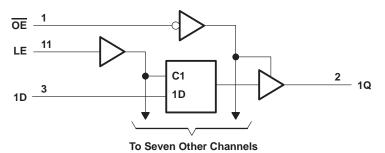
TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–40°C to 85°C	TSSOP – PW	Tape and reel	SN74LVTH373IPWREP	LH373EP	
±					

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each latch)

-							
INPUTS							
LE	D	Q					
Н	Н	Н					
н	L	L					
L	Х	Q ₀ Z					
Х	Х	Z					
	LE H H L	LE D H H L X					

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Current into any output in the low state, I _O	128 mA
Current into any output in the high state, I _O (see Note 2)	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3)	83°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		2.7	3.6	V
VIH	High-level input voltage		2		V
VIL	Low-level input voltage				V
VI	Input voltage				V
ЮН	High-level output current				mA
IOL	Low-level output current			64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	ns/V
$\Delta t / \Delta V_{CC}$	Power-up ramp rate		200		μs/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARA	METER	TEST CONDITIC	MIN	TYP†	MAX	UNIT	
VIK		V _{CC} = 2.7 V,	lj = -18 mA			-1.2	V
		V _{CC} = 2.7 V to 3.6 V,	I _{OH} = −100 μA	V _{CC} -0.2			
∨он		V _{CC} = 2.7 V,	I _{OH} = –8 mA	2.4			V
		$V_{CC} = 3 V$	I _{OH} = -32 mA	2			
		N 0.7.V	I _{OL} = 100 μA			0.2	
		$V_{CC} = 2.7 V$	I _{OL} = 24 mA			0.5	
VOL			I _{OL} = 16 mA			0.4	V
		V _{CC} = 3 V	I _{OL} = 32 mA			0.5	
			I _{OL} = 64 mA			0.55	
		V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			10	
lj -	Control inputs	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			±1	μA
•	Data		$V_{I} = V_{CC}$			1	
	inputs	V _{CC} = 3.6 V	V _I = 0			-5	
l _{off}		$V_{CC} = 0,$	V_{I} or $V_{O} = 0$ to 4.5 V			±100	μΑ
		N 2.V	VI = 0.8 V	75			
10	Data inputs $V_{CC} = 3 V$ $V_{CC} = 3.6 V^{\ddagger},$	$V_{CC} = 3 V$	V _I = 2 V	-75			μΑ
l(hold)		$V_{CC} = 3.6 V^{\ddagger},$	$V_{I} = 0$ to 3.6 V			500 -750	
IOZH		V _{CC} = 3.6 V,	V _O = 3 V			5	μΑ
IOZL		V _{CC} = 3.6 V,	V _O = 0.5 V			-5	μΑ
IOZPU		$V_{CC} = 0$ to 1.5 V, $V_O = 0.5$ V to 3 V, $\overline{OE} = dor$	i't care			±100	μA
IOZPD		$V_{CC} = 1.5$ V to 0, $V_{O} = 0.5$ V to 3 V, $\overline{OE} = dor$	n't care			±100	μA
01.0			Outputs high			0.19	
ICC		$V_{CC} = 3.6 \text{ V}, I_{O} = 0, V_{I} = V_{CC} \text{ or GND}$	Outputs low		5		mA
			Outputs disabled			0.19	1
∆ICC§		$V_{CC} = 3 V$ to 3.6 V, One input at $V_{CC} - 0.6 V$, Other inputs at V_{CC} or GND				0.2	mA
Ci		V _I = 3 V or 0			3		pF
Co		$V_{O} = 3 V \text{ or } 0$			7		pF

[†] All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}C$.

[‡]This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another. § This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		= ۷ _{CC} ± 0.3	3.3 V 3 V	V _{CC} =	2.7 V	UNIT
		MIN	MAX	MIN	MAX	
tw	Pulse duration, LE high	3		3		ns
t _{su}	Setup time, data before LE \downarrow	1.1		0.4		ns
th	Hold time, data after LE \downarrow	1.4		1.4		ns



SN74LVTH373-EP **3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCH** WITH 3-STATE OUTPUTS SCBS770 - NOVEMBER 2003

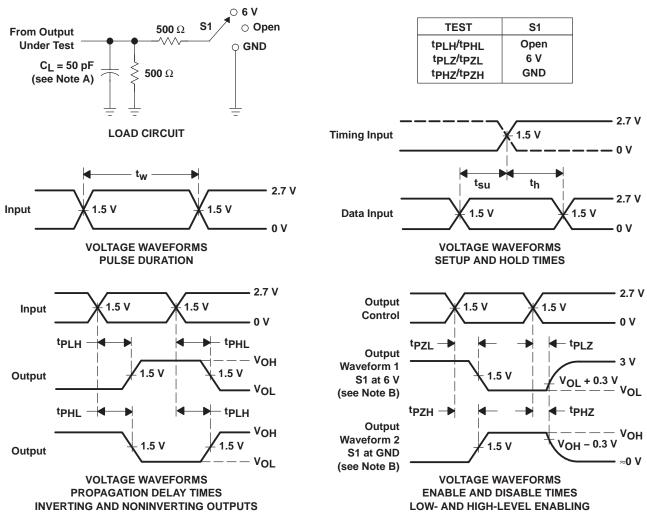
switching characteristics over recommended free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
	(INPUT)	(OUTPUT)	MIN	TYP†	MAX	MIN	MAX	
^t PLH	D	0	1.5	2.6	3.9		4.5	
^t PHL	D	Q		2.6	3.9		4.5	ns
^t PLH		0	1.7	2.7	4.2		4.9	
^t PHL	LE	Q	1.7	2.7	4.2		4.9	ns
^t PZH	OE	0	1.3	3	4.8		5.9	
^t PZL	OE	Q	1.3	3	4.8		5.5	ns
^t PHZ	OE	0	1.9	3	4.6		4.9	
^t PLZ	UE	Q	1.9	3	4.5		4.6	ns

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. Cl includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns. D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
SN74LVTH373IPWREP	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH373EP	Samples
V62/04675-01XE	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH373EP	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN74LVTH373-EP :

• Catalog: SN74LVTH373



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PACKAGE OPTION ADDENDUM

24-Jan-2013

Military: SN54LVTH373

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

P1

(mm)

8.0

w

(mm)

16.0

Pin1

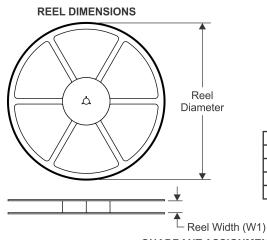
Quadrant

Q1

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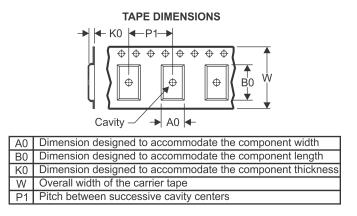
TAPE AND REEL INFORMATION



SN74LVTH373IPWREP

TSSOP

PW



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



330.0

16.4

6.95

7.1

1.6

*/	All dimensions are nominal								
	Device	Package Drawing	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	

2000

20

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH373IPWREP	TSSOP	PW	20	2000	367.0	367.0	38.0

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